JMS

Technology & Market Trends Report on FC-BGA Substrates/2.xD Package Substrates

-2022-

Japan Marketing Survey Co., Ltd.

https://www.jms21.co.jp/

Outline of the Survey-1

1. Objective of the Publication

This report comprehensively grasps the global market trends of FC-BGA Substrates/2.xD Package Substrates, by investigating/analyzing the technology, market trends and supply & demand trends of this market in detail, in order to provide industry-related people with basic information on their business strategy planning.

2. Items of the survey

FC-BGA Substrates/2.xD Package Substrates (by ICs, by Applications, by Layer Counts)

3. Period of the survey

December 2021 through September 2022

4. Method of the Survey

Direct interviews, questionnaires, newspapers, academic, technical journals and internet survey, etc.

5. Remarks

*All of the numerical data in this report is prepared by JMS unless so noted.
*The market sizes are all worldwide basis.
*The data is a calendar year basis.
*The price market was calculated in USD. The exchange rates in 2021 were as follows.
*1USD＝110.7Yen＝1,128KRW＝28.49NTD＝6.57RMB＝0.8522EUR

Outline of the Survey-2

6. Special notes

Abbreviations are used on graphs in this Report. The official names of the package substrate manufacturers are as follows

Abbreviation	Official Name of the Company
Ibiden	IBIDEN CO., LTD.
Shinko	SHINKO ELECTRONIC INDUSTRIES CO., LTD.
Kyocera	KYOCERA Corporation
Toppan	TOPPAN INC.
Unimicron	Unimicron Technology Corporation
Nan Ya	Nan Ya PCB Corporation
Kinsus	KINSUS INTERCONNECT TECHNOLOGY CORP.
ZDT	Zhen Ding Technology Holding Limited
SEMCO	Samsung Electro-Mechanics Co., Ltd.
Simmtech	SIMMTECH Co., Ltd.
KCC	KOREA CIRCUIT CO., LTD.
Daeduck	DAEDUCK ELECTRONICS Co., Ltd.
LG Innotek	LG Innotek Co., Ltd.
AT&S	AT & S Austria Technologie & Systemtechnik Aktiengesellschaft

Focal points of the survey

1. Forecast and analysis the demand and supply trends of this promise market that new manufacturers are constantly entering.

2. Analysis the advanced IC package technology trends by ICs and major manufacturers.

3. Forecast and analysis the global market size of FC-BGA substrates/2.xD Package substrates by applications and layer counts in value, volume and area terms.

4. Analysis the actual sales of major substrate manufacturers by applications/layer counts in both value and volume terms

5. Analysis the supply state to major Semiconductor manufacturers by applications in both value and volume terms

6. Case studies of major substrate manufacturers by country/region.

Table of the Contents

Contents	Page
Summary	1
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates	2
Demand and Supply Analysis of FC-BGA Substrates/2.xD Package Substrates	4
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates for PC	7
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates for Server/AI	9
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates for Game/Others	11
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates for Networking	13
Global Market Overview of FC-BGA Substrates/2.xD Package Substrates for Automotive	15
Sales Ranking of Major Substrate Manufacturers	17
Supply Ranking to Major Semiconductor Manufacturers	18
Customer Information of FC-BGA Substrates/2.xD Package Substrates for PC	19
Customer Information of FC-BGA Substrates/2.xD Package Substrates for Server/AI	20
Customer Information of FC-BGA Substrates/2.xD Package Substrates for Game/Others	21
Customer Information of FC-BGA Substrates/2.xD Package Substrates for Networking	22
Customer Information of FC-BGA Substrates/2.xD Package Substrates for Automotive	23
Sales Status of the Major Substrate Manufacturers	24
Capital Investment Movements for FC-BGA Substrates of the Major Substrate Manufacturers	26

Table of the Contents

Contents	Page
Product Trends of FC-BGA Substrates/2.xD Package Substrates	30
Chapter 1 Technology Trends of Advanced IC Packages	32
1. Miniaturization of Silicon Node	33
2. Packaging Technology Roadmap by ICs	34
3. Types and Outlines of the 2.xD Packages	38
4. Trends of Silicon Interposer(Si-IP)	40
5. Packing Technology Trends of Major Manufacturers	41
Chapter 2 Global Market Trends for FC-BGA Substrates/2.xD Package Substrates	53
1. Global Market Size Forecast for FC-BGA Substrates/2.xD Package Substrates	54
Global Market Size Forecast for FC-BGA Substrates/2.xD Package Substrates by Applications	55
Global Market Size Forecast for FC-BGA Substrates/2.xD Package Substrates by Layer Counts	63
2. Global Market Trends by Segments	71
Global Market Size of FC-BGA Substrates/2.xD Package Substrates by Applications/Layer Counts	72
3. Actual Sales of Major Substrate Manufacturers	83
Major Substrate Manufacturers’ Actual Sales by Applications	84
Major Substrate Manufacturers’ Actual Sales by Layer Counts	87
Major Substrate Manufacturers’ Actual Sales of PC-MPU Substrates	94

Table of the Contents

Contents	Page
Major Substrate Manufacturers’ Actual Sales of PC-GPU Substrates	97
Major Substrate Manufacturers’ Actual Sales of PC-Chipset Substrates	100
Major Substrate Manufacturers’ Actual Sales of Server/AI-MPU Substrates	103
Major Substrate Manufacturers’ Actual Sales of Server/AI-GPU Substrates	107
Major Substrate Manufacturers’ Actual Sales of Game/Others-MPU Substrates	110
Major Substrate Manufacturers’ Actual Sales of Game/Others-GPU Substrates	113
Major Substrate Manufacturers’ Actual Sales of Networking-FPGA/ASIC/Others	116
Major Substrate Manufacturers’ Actual Sales of Automotive-FPGA/ASIC/Others	119
Major Substrate Manufacturers’ Actual Sales of Others-FPGA/ASIC/Others	122
Major Substrate Manufacturers’ Actual Sales by Supply Chain	125
4. Supply State to Major Semiconductor Manufacturers	138
Supply State to Intel	143
Supply State to AMD	146
Supply State to Nvidia	149
Supply State to Xilinx	152
Supply State to Broadcom	155
Supply State to Apple	158

Table of the Contents

Contents	Page
Supply State to Marvell	161
Supply State to Renesas	164
Supply State to NXP	167
Supply State to Texas Instruments	170
Supply State to Samsung	173
Supply State to Microchip	176
Supply State to IBM	178
Supply State to Kioxia	180
Supply State to STMicroelectronics	182
Supply State to MediaTek	184
Supply State to Oracle	187
Supply State to Micron	189
Supply State to SK Hynix	191
Supply State to Qualcomm	193
Supply State to Other Semiconductor Manufacturers	195
Chapter 3 Case Studies of Major Substrate Manufacturers	198
Japanese Manufacturers	199

Table of the Contents

Contents	Page
IBIDEN CO., LTD.	200
SHINKO ELECTRONIC INDUSTRIES CO., LTD.	207
KYOCERA Corporation	216
TOPPAN INC.	224
Taiwanese Manufacturers	234
Unimicron Technology Corporation	235
Nan Ya PCB Corporation	244
KINSUS INTERCONNECT TECHNOLOGY CORP.	253
Zhen Ding Technology Holding Limited	260
Korean Manufacturers	265
Samsung Electro-Mechanics Co., Ltd.	266
SIMMTECH Co., Ltd.	275
KOREA CIRCUIT CO., LTD.	280
DAEDUCK ELECTRONICS Co., Ltd.	286
LG Innotek Co., Ltd.	294
European Manufacturers	298
AT & S Austria Technologie & Systemtechnik Aktiengesellschaft	299

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